

ATIR0811S

Photointerrupter - Reflective Type

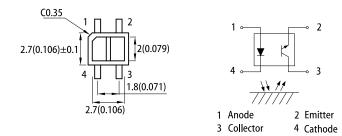
FEATURES

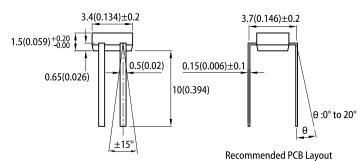
- · Compact and thin
- · Visible light cut-off type
- High sensitivity
- RoHS compliant

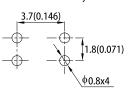
APPLICATIONS

- Cassette tape recorders, VCRs
- · Floppy disk drives
- · Various microcomputerized control equipment

PACKAGE DIMENSIONS







- Notes:

 1. All dimensions are in millimeters (inches).

 2. Tolerance is ±0.25(0.01") unless otherwise noted.

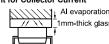
 3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Parameter		Symbol	Value				Units	Test Conditions	
Parameter			Code.	Min.	Тур.	Max.	UiillS	rest Conditions	
Input	Forward voltage		V_{F}		1.0	1.2	1.5	V	I _F =20mA
	Reverse current		I _R		-	-	10	μΑ	V _R =6V
Output	Collector dark current		I _{CEO}		-	10 ⁻⁹	10 ⁻⁷	Α	V _{CE} =20V
Transfer characteristics	Collector Current [1]		I _C	E	10	-	120	μΑ I _F =4mA,V _C	
				F	100	-	250		I _F =4mA,V _{CE} =2V
				G	200	-	400		
	Leak Current [2]		I _{LEAK}		-	-	0.1	μΑ	I _F =4mA,V _{CE} =2V
	Response time	Rise time	t _r		-	20	100	μs	V _{CE} =2V, I _C =100μA R _L =1K Ω, d=1mm
		Fall time	t _f		-	20	100	μs	

Notes:

Test Condition and Arrangement for Collector Current





^{2.3.} Excess driving current and/or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

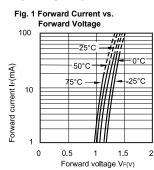


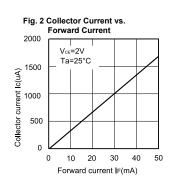
ABSOLUTE MAXIMUM RATINGS at $T_A=25$ °C

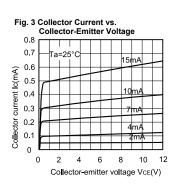
	Parameter	Symbol	Rating	Unit
Input	Forward current	l _F	50	mA
	Reverse voltage	V _R	6	V
	Power dissipation	P _D	75	mW
	Peak Forward Current (Pulse Width ≤100µs, Duty Cycle=1%)	I _{FP}	1	A
Output	Collector-emitter voltage	V _{CEO}	35	V
	Emitter-collector voltage	V _{ECO}	6	V
	Collector current	Ic	20	mA
	Collector power dissipation	P _C	75	mW
Operating temperature		T _{opr}	-25~+85	°C
Storage temperature		T _{stg}	-40~+100	°C
Soldering temperature (1/16 inch from body for 5 seconds)		T _{sol}	260	°C

Note

TECHNICAL DATA







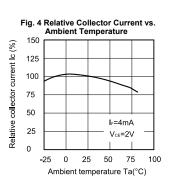
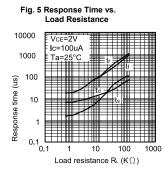
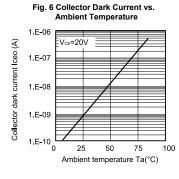


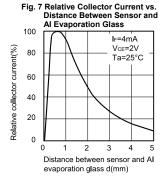
Fig. 8 Relative Collector Current vs.

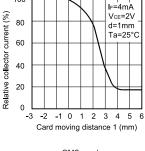
100

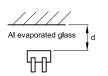
Card Moving Distance (1)

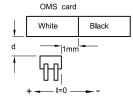






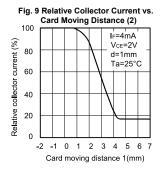


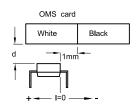




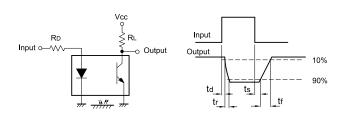
^{1.} Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.



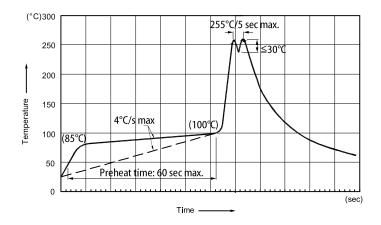




Test Circuit for Response Time



RECOMMENDED WAVE SOLDERING PROFILE



Notes:

- 1. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C

- temperature of 260°C.

 2. Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).

 3. Do not apply stress to the epoxy resin while the temperature is above 85°C.

 4. Fixtures should not incur stress on the component when mounting and during soldering process.

 5. SAC 305 solder alloy is recommended.

 6. No more than one wave soldering pass.

PACKING & LABEL SPECIFICATIONS

